

Pre Conference Workshop on Semiconductor Packaging

Hosted by



Date: 05th Sep'23
Time: 13:00 – 17:00 hrs
Venue: New Lecture Hall
Complex, IIT Tirupati

Registration fee:

Students	Rs. 500/-
Academic Faculty	Rs. 1000/-

50% Discount for PFAM 2023 registered participants

Register Now

www.pfam29.com



Overview:

This pre-conference workshop is jointly hosted by Central Manufacturing Technology Institute (CMTI), Bengaluru, and IIT Tirupati to bring in the synergy of semiconductor packaging and allied processes for device and technology development in both academic and industrial capacity.

Semiconductor devices / Microsystems are being used abundantly across various domains for numerous applications.

Fabricating these devices as per the application requirement is a vast process.

By undergoing this pre-conference workshop, an individual shall be able to understand the design requirements, and fabrication process flow and also meet the packaging requirements of the microdevices or sensors as per the end-user demands. Eminent speakers shall deliver impactful lectures on the mentioned topics including the funding opportunities and present semiconductor ecosystem in the country.

Target Participants:

Students, academicians, researchers, and product developers in the field of sensors, semiconductors, MEMS, and electronics.

The following technical aspects shall be covered in the training course.

- Basics of electronics packaging
- 2D packaging process technologies and case studies
- Advanced 3D and wafer level packaging methodologies
- Fabrication processes, characterization, testing & validation of products for performance evaluation.